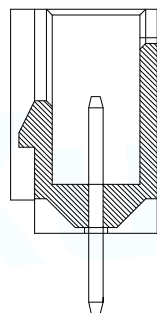
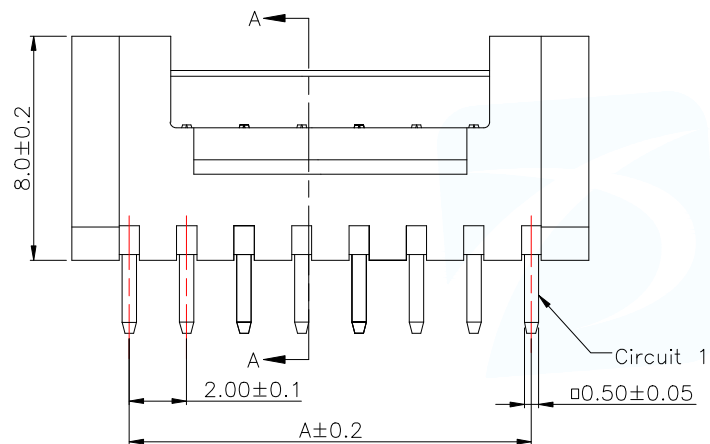
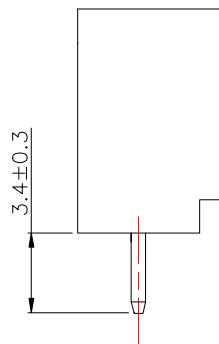
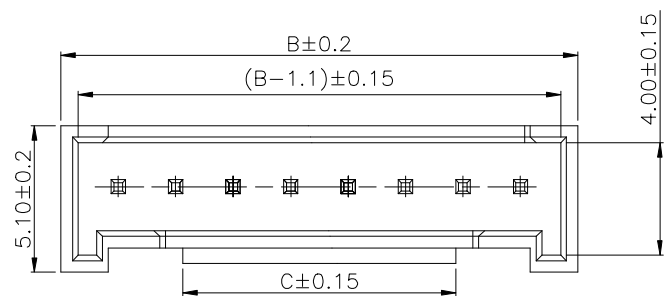
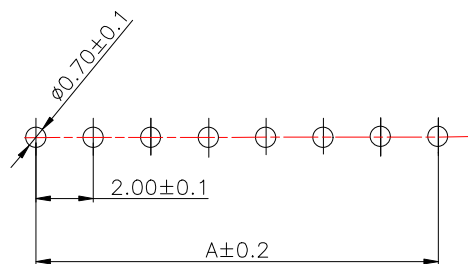


MAPX	MODIFICATION	DATE	DRAW	APPROVE



SECTION A-A

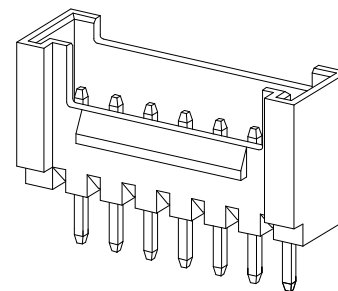
Part No	Pin	A	B	C
WAFER-HY2.0-2PZZ	2	2.00	6.00	2.50
WAFER-HY2.0-3PZZ	3	4.00	8.00	2.50
WAFER-HY2.0-4PZZ	4	6.00	10.00	3.50
WAFER-HY2.0-5PZZ	5	8.00	12.00	5.50
WAFER-HY2.0-6PZZ	6	10.00	14.00	7.50
WAFER-HY2.0-7PZZ	7	12.00	16.00	9.50
WAFER-HY2.0-8PZZ	8	14.00	18.00	11.50
WAFER-HY2.0-9PZZ	9	16.00	20.00	13.50
WAFER-HY2.0-10PZZ	10	18.00	22.00	15.50
WAFER-HY2.0-11PZZ	11	20.00	24.00	15.50
WAFER-HY2.0-12PZZ	12	22.00	26.00	15.50
WAFER-HY2.0-13PZZ	13	24.00	28.00	15.50
WAFER-HY2.0-14PZZ	14	26.00	30.00	15.50
WAFER-HY2.0-15PZZ	15	28.00	32.00	15.50



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

技术要求:

1. 塑件材料: PA66 (UL-94V-0)
2. 接触件: 黄铜镀锡
3. 接触电阻: $\leq 10m\Omega$
4. 绝缘电阻: $\geq 100M\Omega$
5. 额定电压: 250V AC DC
6. 额定电流: 2.0A AC DC
7. 耐压: 能承受 1000V AC/Minute
8. 工作温度: $-25^{\circ}\sim+85^{\circ}$
9. 可焊性试验: 浸锡面积 $\geq 95\%$ 温度 235 $\pm 5^{\circ}$ 时间 2.5 ± 0.5 秒
10. 铅和镉等六大有害物质含量要符合环保要求。



2	端子Contact	黄铜	N*1	电镀(锡): 整个表面镀底镍 30u"MIN, 再镀锡 80u"MIN
1	基座Wafer	LCP(UL94V-0)	1	白色
序号	名称	材料	数量	备注

MANUFACTURE DWG		东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co., Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: WAFER HY2.0MM 直针
DECIMALS: .X±0.20			PAR WAFER-HY2.0-NPZZ
ANGLES: ±2'			DWN
.XX±0.10			CHKD
.XXX±0.05		APVD	SCALE 1:1 UNIT:MM
CUSTOMER COPY		SIZE: A4	UNIT:MM
		SHEET: 1F1	REV: A